# **Hex Non-Inverting 3-State Buffer**

The MC14503B is a hex non-inverting buffer with 3-state outputs, and a high current source and sink capability. The 3-state outputs make it useful in common bussing applications. Two disable controls are provided. A high level on the Disable A input causes the outputs of buffers 1 through 4 to go into a high impedance state and a high level on the Disable B input causes the outputs of buffers 5 and 6 to go into a high impedance state.

## **Features**

- 3–State Outputs
- TTL Compatible Will Drive One TTL Load Over Full Temperature Range
- Supply Voltage Range = 3.0 Vdc to 18 Vdc
- Two Disable Controls for Added Versatility
- Pin for Pin Replacement for MM80C97 and 340097
- Pb-Free Packages are Available\*

## MAXIMUM RATINGS (Voltages Referenced to V<sub>SS</sub>) (Note 1)

Parameter	Symbol	Value	Unit
DC Supply Voltage Range	$V_{DD}$	-0.5 to +18.0	V
Input or Output Voltage Range (DC or Transient)	$V_{in}$ , $V_{out}$	-0.5 to V <sub>DD</sub> + 0.5	V
Input Current (DC or Transient) per Pin	I <sub>in</sub>	±10	mA
Output Current (DC or Transient) per Pin	l <sub>out</sub>	±25	mA
Power Dissipation, per Package (Note 2)	P <sub>D</sub>	500	mW
Ambient Temperature Range	T <sub>A</sub>	-55 to +125	°C
Storage Temperature Range		-65 to +150	°C
Lead Temperature (8–Second Soldering)		260	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

- Maximum Ratings are those values beyond which damage to the device may occur.
- Temperature Derating:

Plastic "P and D/DW" Packages: - 7.0 mW/°C From 65°C To 125°C

This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high–impedance circuit. For proper operation,  $V_{in}$  and  $V_{out}$  should be constrained to the range  $V_{SS} \leq (V_{in} \text{ or } V_{out}) \leq V_{DD}$ .

Unused inputs must always be tied to an appropriate logic voltage level (e.g., either  $V_{SS}$  or  $V_{DD}$ ). Unused outputs must be left open.



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MARKING DIAGRAMS



PDIP-16 P SUFFIX CASE 648 16hhhhhhhhhhhhh MC14503BCP O AWLYYWWG



SOIC-16 D SUFFIX CASE 751B 

SOEIAJ-16 F SUFFIX CASE 966 A = Assembly Location

WL, L = Wafer Lot
YY, Y = Year
WW, W = Work Week
G = Pb-Free Package

## **ORDERING INFORMATION**

See detailed ordering and shipping information in the package dimensions section on page 2 of this data sheet.

<sup>\*</sup>For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

## **PIN ASSIGNMENT**

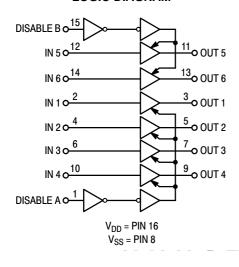
DIS A	1 •	16 J V <sub>DD</sub>
IN 1 [	2	15 DIS B
OUT 1	3	14 ] IN 6
IN 2 [	4	13 OUT 6
OUT 2	5	12 ] IN 5
IN 3 🛚	6	11 OUT 5
OUT 3	7	10 🛮 IN 4
V <sub>SS</sub> [	8	9 OUT 4

## **TRUTH TABLE**

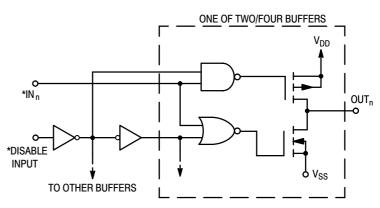
In <sub>n</sub>	Appropriate Disable Input	Out <sub>n</sub>
0	0	0
1	0	1
Х	1	High Impedance

X = Don't Care

## **LOGIC DIAGRAM**



## **CIRCUIT DIAGRAM**



\*Diode protection on all inputs (not shown)

## **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
MC14503BCP	PDIP-16	
MC14503BCPG	PDIP-16 (Pb-Free)	25 / Rail
MC14503BD	SOIC-16	
MC14503BDG	SOIC-16 (Pb-Free)	48 / Rail
MC14503BDR2	SOIC-16	
MC14503BDR2G	SOIC-16 (Pb-Free)	2500 / Tape & Reel
MC14503BFEL	SOEIAJ-16	
MC14503BFELG	SOEIAJ-16 (Pb-Free)	2000 / Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

## **ELECTRICAL CHARACTERISTICS** (Voltages Referenced to V<sub>SS</sub>)

				- 5	5°C		25°C		125	°C	
Characteristic		Symbol	V <sub>DD</sub> Vdc	Min	Max	Min	Typ (Note 3)	Max	Min	Max	Unit
Output Voltage V <sub>in</sub> = 0	"0" Level	V <sub>OL</sub>	5.0 10 15	- - -	0.05 0.05 0.05	- - -	0 0 0	0.05 0.05 0.05	- - -	0.05 0.05 0.05	Vdc
$V_{in} = V_{DD}$	"1" Level	V <sub>OH</sub>	5.0 10 15	4.95 9.95 14.95	- - -	4.95 9.95 14.95	5.0 10 15	- - -	4.95 9.95 14.95	- - -	Vdc
Input Voltage (V <sub>O</sub> = 3.6 or 1.4 Vdc) (V <sub>O</sub> = 7.2 or 2.8 Vdc) (V <sub>O</sub> = 11.5 or 3.5 Vdc)	"0" Level	V <sub>IL</sub>	5.0 10 15	1 1	1.5 3.0 4.0	1 1 1	2.25 4.50 6.75	1.5 3.0 4.0	- - -	1.5 3.0 4.0	Vdc
(V <sub>O</sub> = 1.4 or 3.6 Vdc) (V <sub>O</sub> = 2.8 or 7.2 Vdc) (V <sub>O</sub> = 3.5 or 11.5 Vdc)	"1" Level	V <sub>IH</sub>	5.0 10 15	3.5 7.0 11	1 1 1	3.5 7.0 11	2.75 5.50 8.25	1 1 1	3.5 7.0 11		Vdc
Output Drive Current ( $V_{OH} = 2.5 \text{ Vdc}$ ) ( $V_{OH} = 2.5 \text{ Vdc}$ ) ( $V_{OH} = 4.6 \text{ Vdc}$ ) ( $V_{OH} = 9.5 \text{ Vdc}$ ) ( $V_{OH} = 13.5 \text{ Vdc}$ )	Source	ГОН	4.5 5.0 5.0 10 15	- 4.3 - 5.8 - 1.2 - 3.1 - 8.2		- 3.6 - 4.8 - 1.02 - 2.6 - 6.8	- 5.0 - 6.1 - 1.4 - 3.7 - 14.1		- 2.5 - 3.0 - 0.7 - 1.8 - 4.8		mAdc
$(V_{OL} = 0.4 \text{ Vdc})$ $(V_{OL} = 0.4 \text{ Vdc})$ $(V_{OL} = 0.5 \text{ Vdc})$ $(V_{OL} = 1.5 \text{ Vdc})$	Sink	I <sub>OL</sub>	4.5 5.0 10 15	2.2 2.6 6.5 19.2		1.8 2.1 5.5 16.1	2.1 2.3 6.2 25		1.2 1.3 3.8 11.2	- - -	mAdc
Input Current		I <sub>in</sub>	15	-	± 0.1	-	±0.00001	± 0.1	-	± 1.0	μAdc
Input Capacitance, (V <sub>in</sub> = 0	)	C <sub>in</sub>	-	_	-	-	5.0	7.5	-	-	pF
Quiescent Current, (Per Pa	ickage)	Ja	5.0 10 15	_ <b>-</b>	1.0 _ 2.0 4.0	_ <del>-</del> _	0.002 0.004 0.006	1.0 2.0 4.0	- - -	30 60 120	μAdc
Total Supply Current (Note (Dynamic plus Quiescer Per Package) (C <sub>L</sub> = 50 pF on all output (All outputs switching, 50% Duty Cycle)	nt,	I <sub>T</sub>	5.0 $I_T = (2.5 \mu\text{A/kHz})  f + I_{DD}$ 10 $I_T = (6.0 \mu\text{A/kHz})  f + I_{DD}$ 15 $I_T = (10 \mu\text{A/kHz})  f + I_{DD}$			μAdc					
3-State Output Leakage C	urrent	I <sub>TL</sub>	15	_	± 0.1	_	± 0.0001	± 0.1	_	± 3.0	μAdc

Data labelled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.
 The formulas given are for the typical characteristics only at 25°C.
 To calculate total supply current at loads other than 50 pF: I<sub>T</sub>(C<sub>L</sub>) = I<sub>T</sub>(50 pF) + (C<sub>L</sub> – 50) Vfk where: I<sub>T</sub> is in μA (per package), C<sub>L</sub> in pF, V = (V<sub>DD</sub> – V<sub>SS</sub>) in volts, f in kHz is input frequency, and k = 0.006.

## SWITCHING CHARACTERISTICS (Note 6) (C $_L$ = 50 pF, $T_A$ = $25^{\circ}C)$

			All Ty	pes	
Characteristic	Symbol	V <sub>DD</sub> V <sub>CC</sub>	Typ (Note 7)	Max	Unit
Output Rise Time $t_{TLH} = (0.5 \text{ ns/pF}) C_L + 20 \text{ ns}$ $t_{TLH} = (0.3 \text{ ns/pF}) C_L + 8.0 \text{ ns}$ $t_{TLH} = (0.2 \text{ ns/pF}) C_L + 8.0 \text{ ns}$	tтLH	5.0 10 15	45 23 18	90 45 35	ns
Output Fall Time $t_{THL} = (0.5 \text{ ns/pF}) C_L + 20 \text{ ns}$ $t_{THL} = (0.3 \text{ ns/pF}) C_L + 8.0 \text{ ns}$ $t_{THL} = (0.2 \text{ ns/pF}) C_L + 8.0 \text{ ns}$	t⊤HL	5.0 10 15	45 23 18	90 45 35	ns
Turn–Off Delay Time, all Outputs $t_{PLH} = (0.3 \text{ ns/pF}) C_L + 60 \text{ ns}$ $t_{PLH} = (0.15 \text{ ns/pF}) C_L + 27 \text{ ns}$ $t_{PLH} = (0.1 \text{ ns/pF}) C_L + 20 \text{ ns}$	<sup>†</sup> PLH	5.0 10 15	75 35 25	150 70 50	ns
Turn–On Delay Time, all Outputs $t_{PHL} = (0.3 \text{ ns/pF}) \text{ C}_L + 60 \text{ ns}$ $t_{PHL} = (0.15 \text{ ns/pF}) \text{ C}_L + 27 \text{ ns}$ $t_{PHL} = (0.1 \text{ ns/pF}) \text{ C}_L + 20 \text{ ns}$	<sup>†</sup> PHL	5.0 10 15	75 35 25	150 70 50	ns
3–State Propagation Delay Time Output "1" to High Impedance	t <sub>PHZ</sub>	5.0 10 15	75 40 35	150 80 70	ns
Output "0" to High Impedance	t <sub>PLZ</sub>	5.0 10 15	80 40 35	160 80 70	ns
High Impedance to "1" Level	t <sub>PZH</sub>	5.0 10 15	65 25 20	130 50 40	ns
High Impedance to "0" Level	t <sub>PZL</sub>	5.0 10 15	100 35 25	200 70 50	ns

- 6. The formulas given are for the typical characteristics only at 25°C.
  7. Data labelled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.

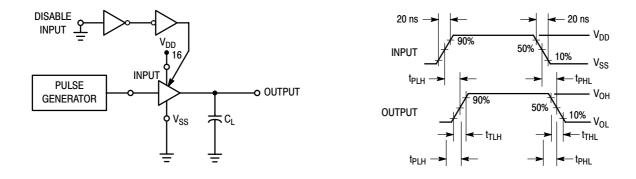
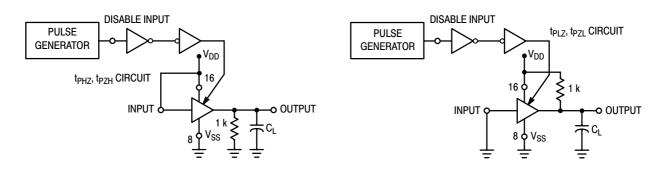


Figure 1. Switching Time Test Circuit and Waveforms (t<sub>TLH</sub>, t<sub>THL</sub>, t<sub>PHL</sub>, and t<sub>PLH</sub>)



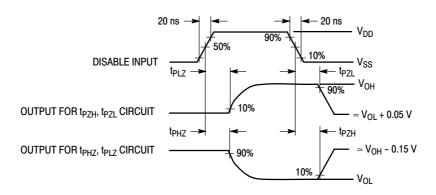
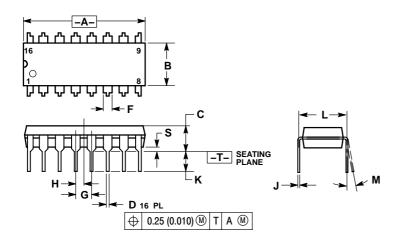


Figure 2. 3-State AC Test Circuit and Waveforms  $(t_{PLZ}, t_{PHZ}, t_{PZH}, t_{PZL})$ 

## PACKAGE DIMENSIONS

## PDIP-16 CASE 648-08 **ISSUE T**



#### NOTES:

- NOTES:

  1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

  2. CONTROLLING DIMENSION: INCH.

  3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.

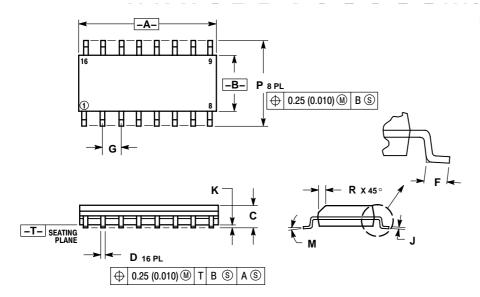
  4. DIMENSION B DOES NOT INCLUDE

- MOLD FLASH.

  5. ROUNDED CORNERS OPTIONAL.

	INC	HES	MILLIN	IETERS
DIM	MIN	MAX	MIN	MAX
Α	0.740	0.770	18.80	19.55
В	0.250	0.270	6.35	6.85
С	0.145	0.175	3.69	4.44
D	0.015	0.021	0.39	0.53
F	0.040	0.70	1.02	1.77
G	0.100	BSC	2.54	BSC
Н	0.050	BSC	1.27 BSC	
J	0.008	0.015	0.21	0.38
K	0.110	0.130	2.80	3.30
L	0.295	0.305	7.50	7.74
М	0°	10 °	0°	10 °
S	0.020	0.040	0.51	1.01

## SOIC-16 CASE 751B-05 **ISSUE J**



## NOTES:

- NOTES:

  1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

  2. CONTROLLING DIMENSION: MILLIMETER.

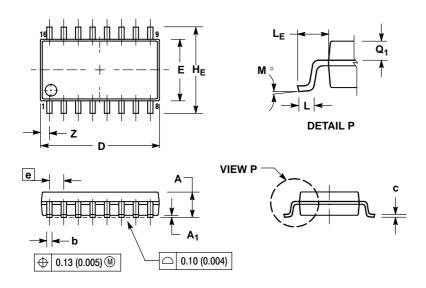
  3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.

  4. MAXIMUM MOLD PROTRUSION 0.15 (0.006)
- MAXIMUM MOLD PHOTHUSION 0.13 (0.000)
  PER SIDE.
  DIMENSION D DOES NOT INCLUDE DAMBAR
  PROTRUSION. ALLOWABLE DAMBAR
  PROTRUSION SHALL BE 0.127 (0.005) TOTAL
  IN EXCESS OF THE D DIMENSION AT
  MAXIMUM MATERIAL CONDITION.

	MILLIMETERS		INC	HES
DIM	MIN	MAX	MIN	MAX
Α	9.80	10.00	0.386	0.393
В	3.80	4.00	0.150	0.157
С	1.35	1.75	0.054	0.068
D	0.35	0.49	0.014	0.019
F	0.40	1.25	0.016	0.049
G	1.27	1.27 BSC		BSC
J	0.19	0.25	0.008	0.009
K	0.10	0.25	0.004	0.009
M	0°	7°	0°	7°
P	5.80	6.20	0.229	0.244
R	0.25	0.50	0.010	0.019

## PACKAGE DIMENSIONS

## SOEIAJ-16 CASE 966-01 **ISSUE A**



#### NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14 5M 1982
- CONTROLLING DIMENSION: MILLIMETER.
- B. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS AND ARE MEASURED AT THE PARTING LINE. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
  TERMINAL NUMBERS ARE SHOWN FOR
- REFERENCE ONLY.

  5. THE LEAD WIDTH DIMENSION (b) DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE LEAD WIDTH DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT, MINIMUM SPACE BETWEEN PROTRUSIONS AND ADJACENT LEAD TO BE 0.46 ( 0.018)

	MILLIMETERS		INC	HES
DIM	MIN	MAX	MIN	MAX
Α		2.05		0.081
A <sub>1</sub>	0.05	0.20	0.002	0.008
b	0.35	0.50	0.014	0.020
С	0.10	0.20	0.007	0.011
D	9.90	10.50	0.390	0.413
Е	5.10	5.45	0.201	0.215
е	1.27 BSC		0.050	BSC
HE	7.40	8.20	0.291	0.323
L	0.50	0.85	0.020	0.033
LE	1.10	1.50	0.043	0.059
M	0 °	10°	0 °	10°
Q <sub>1</sub>	0.70	0.90	0.028	0.035
Z		0.78		0.031

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